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Amendment
Dec 11/14/04

IN THE CLAIMS:

Please cancel claims 8, 9, 19-35, 37 and 39-46 without prejudice.

Kindly amend claims 1 and 38 and add new claims 47-57 as follows:

1. (Currently amended) A circuit-connecting material interposed between facing circuit electrodes electrically connecting the electrodes in the pressing direction after curing by heat and pressure either by direct contact or via conductive particles present in the material, wherein:

the circuit-connecting material comprises the following components (1) to (3):

- (1) a curing agent capable of generating free radicals upon heating;
- (2) a hydroxyl-group-containing resin having a molecular weight of 10,000 or more, wherein the hydroxyl-group-containing resin is at least one of polyvinyl butyral, polyvinyl formal, polyamide, polyester, phenol resin, epoxy resin and phenoxy resin; and
- (3) a radical-polymerizable substance.

2. (Original) The circuit-connecting material according to claim 1, wherein said curing agent capable of generating free radicals upon heating has a 10-hour half-life temperature of 40°C or above and a 1-minute half-life temperature of 180°C or below.

3-35. (Canceled)

³
~~26.~~ (Previously presented) The circuit-connecting material according to claim 1, which contains conductive particles.

37. (Canceled)

~~38.~~⁵ (Currently amended) The circuit-connecting material according to claim ~~47~~⁴, which contains conductive particles.

39-46. (Canceled)

~~47.~~⁴ (New) A circuit-connecting material interposed between facing circuit electrodes electrically connecting the electrodes in the pressing direction after curing by heat and pressure either by direct contact or via conductive particles present in the material, wherein:

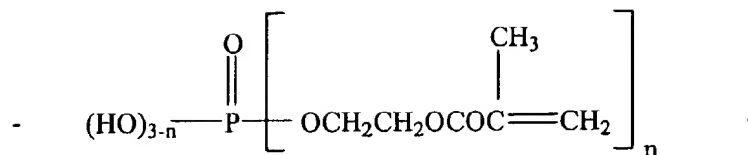
the circuit-connecting material comprises the following components (1) to (3):

- (1) a curing agent capable of generating free radicals upon heating, wherein said curing agent is a peroxyester;
- (2) a hydroxyl-group-containing resin having a molecular weight of 10,000 or more; and
- (3) a radical-polymerizable substance.

~~48.~~⁶ (New) A circuit-connecting material interposed between facing circuit electrodes electrically connecting the electrodes in the pressing direction after curing by heat and pressure either by direct contact or via conductive particles present in the material, wherein:

the circuit-connecting material comprises the following components (1) to (3):

- (1) a curing agent capable of generating free radicals upon heating;
- (2) a hydroxyl-group-containing resin having a molecular weight of 10,000 or more; and
- (3) a radical-polymerizable substance represented by the following chemical formula (a):



... (a)

wherein n is an integer of 1 to 3.

⁷
~~49.~~ (New) The circuit-connecting material according to claim ⁶~~48~~, which contains conductive particles.

⁸
~~50.~~ (New) A circuit-connecting material interposed between facing circuit electrodes electrically connecting the electrodes in the pressing direction after curing by heat and pressure either by direct contact or via conductive particles present in the material, wherein:

the circuit-connecting material comprises the following components (1) to (3):

- (1) a curing agent capable of generating free radicals upon heating;
- (2) a phenoxy resin that is a hydroxyl-group-containing resin having a molecular weight of 10,000 or more; and
- (3) a radical-polymerizable substance.

⁹
~~51.~~ (New) The circuit-connecting material according to claim ⁸~~50~~, which contains conductive particles.

¹⁰
~~52.~~ (New) A circuit-connecting material interposed between facing circuit electrodes electrically connecting the electrodes in the pressing direction after curing by heat and pressure either

by direct contact or via conductive particles present in the material, wherein:

the circuit-connecting material comprises the following components (1) to (3):

- (1) a curing agent capable of generating free radicals upon heating;
- (2) a hydroxyl-group-containing resin having a molecular weight of 10,000 or more, wherein the hydroxyl-group-containing resin is a phenoxy resin modified with an carboxyl-group-containing elastomer; and
- (3) a radical-polymerizable substance.

¹¹
~~53.~~ (New) The circuit-connecting material according to claim ¹⁰~~52~~, which contains conductive particles.

¹²
~~54.~~ (New) A circuit-connecting material interposed between facing circuit electrodes electrically connecting the electrodes in the pressing direction after curing by heat and pressure either by direct contact or via conductive particles present in the material, wherein:

the circuit-connecting material comprises the following components (1) to (3):

- (1) a curing agent capable of generating free radicals upon heating;
- (2) a hydroxyl-group-containing resin having a molecular weight of 10,000 or more, wherein the hydroxyl-group-containing resin is a phenoxy resin modified with an epoxy-group-containing elastomer and
- (3) a radical-polymerizable substance.

¹³
~~55.~~ (New) The circuit-connecting material according to claim ¹²~~54~~, which contains conductive particles.

~~56.~~¹⁴ (New) A circuit-connecting material interposed between facing circuit electrodes electrically connecting the electrodes in the pressing direction after curing by heat and pressure either by direct contact or via conductive particles present in the material, wherein:

the circuit-connecting material comprises the following components (1) to (3):

- (1) a curing agent capable of generating free radicals upon heating;
- (2) a hydroxyl-group-containing resin having a molecular weight of 10,000 or more; and
- (3) a radical-polymerizable substance, and

wherein the circuit-connecting material contains an acrylic rubber.

~~57.~~¹⁵ (New) The circuit-connecting material according to claim ~~56.~~¹⁴, which contains conductive particles.